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OPTICAL SEMICONDUCTOR COMPONENT AND METHOD OF
MANUFACTURE

Abstract of the Disclosure

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An optical semiconductor component includes a semiconductor substrate (120) and a packaging material (140) located over the semiconductor substrate. The packaging material includes an optically transparent cycloaliphatic polymer (142, 242, 400, 600). A method of manufacturing the component includes mixing a monomer (300, 500) of the polymer with a catalyst to form the packaging material, filtering the packaging material, applying the packaging material, and curing the packaging material.

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